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(54) **DUAL-MODE DATACENTER COOLING SYSTEM**

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(57)

ABSTRACT

A system includes one or more first cooling loops to cool one or more first components within one or more servers having a first power density, and one or more second cooling loops to cool one or more second components within the one or more servers having a second power density. The system can flow first coolant to cold plates to cool high-power server components and flow second coolant to cool low-power server components by immersion cooling.

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